

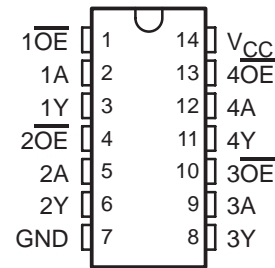
SN74LVTH125-EP 3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

SCBS765 – NOVEMBER 2003

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
- **Enhanced Diminishing Manufacturing Sources (DMS) Support**
- **Enhanced Product-Change Notification**
- **Qualification Pedigree†**
- **Supports Mixed-Mode Signal Operation (5-V Input and Output Voltages With 3.3-V V_{CC})**
- **Supports Unregulated Battery Operation Down to 2.7 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$**
- **I_{off} and Power-Up 3-State Support Hot Insertion**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

† Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

PW PACKAGE
(TOP VIEW)



description/ordering information

This bus buffer is designed specifically for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment.

The SN74LVTH125 features independent line drivers with 3-state outputs. Each output is in the high-impedance state when the associated output-enable (\overline{OE}) input is high.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

When V_{CC} is between 0 and 1.5 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

ORDERING INFORMATION

T_A	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	TSSOP – PW	Tape and reel		
–40°C to 85°C	TSSOP – PW	Tape and reel	SN74LVTH125IPWREP	LH125EP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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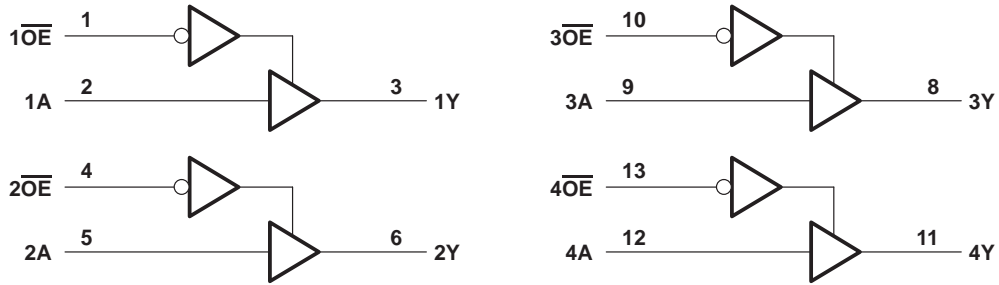
SN74LVTH125-EP
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WITH 3-STATE OUTPUTS

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FUNCTION TABLE
 (each buffer)

INPUTS		OUTPUT
\overline{OE}	A	Y
L	H	H
L	L	L
H	X	Z

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or power-off state, V_O (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high state, V_O (see Note 1)	–0.5 V to $V_{CC} + 0.5$ V
Current into any output in the low state, I_O	128 mA
Current into any output in the high state, I_O (see Note 2)	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$)	–50 mA
Package thermal impedance, θ_{JA} (see Note 3)	113°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 4)

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2.7	3.6	V
V_{IH}	High-level input voltage	2		V
V_{IL}	Low-level input voltage		0.8	V
V_I	Input voltage		5.5	V
I_{OH}	High-level output current		–32	mA
I_{OL}	Low-level output current		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate		10	ns/V
				Outputs enabled
$\Delta t/\Delta V_{CC}$	Power-up ramp rate	200		μs/V
T_A	Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



SN74LVTH125-EP

3.3-V ABT QUADRUPLE BUS BUFFER WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V _{IK}		V _{CC} = 2.7 V,	I _I = -18 mA			-1.2	V	
V _{OH}		V _{CC} = 2.7 V to 3.6 V,	I _{OH} = -100 μA	V _{CC} -0.2			V	
		V _{CC} = 2.7 V,	I _{OH} = -8 mA	2.4				
		V _{CC} = 3 V,	I _{OH} = -32 mA	2				
V _{OL}		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2	V	
			I _{OL} = 24 mA			0.5		
		V _{CC} = 3 V	I _{OL} = 16 mA			0.4		
			I _{OL} = 32 mA			0.5		
			I _{OL} = 64 mA			0.55		
I _I		V _{CC} = 0 or 3.6 V,	V _I = 5.5 V			10	μA	
		Control inputs	V _{CC} = 3.6 V,	V _I = V _{CC} or GND				±1
		Data inputs	V _{CC} = 3.6 V	V _I = V _{CC}				1
			V _I = 0			-5		
I _{off}		V _{CC} = 0,	V _I or V _O = 0 to 4.5 V			±100	μA	
I _I (hold)		Data inputs	V _{CC} = 3 V	V _I = 0.8 V	75		μA	
				V _I = 2 V	-75			
			V _{CC} = 3.6 V‡,	V _I = 0 to 3.6 V				±500
I _{OZH}		V _{CC} = 3.6 V,	V _O = 3 V			5	μA	
I _{OZL}		V _{CC} = 3.6 V,	V _O = 0.5 V			-5	μA	
I _{OZPU}		V _{CC} = 0 to 1.5 V, V _O = 0.5 V to 3 V, \overline{OE} = don't care					±50	μA
I _{OZPD}		V _{CC} = 1.5 V to 0, V _O = 0.5 V to 3 V, \overline{OE} = don't care					±50	μA
I _{CC}		V _{CC} = 3.6 V, I _O = 0, V _I = V _{CC} or GND		Outputs high		0.12	0.19	mA
				Outputs low		4.5	7	
				Outputs disabled		0.12	0.19	
ΔI _{CC} §		V _{CC} = 3 V to 3.6 V, One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND					0.2	mA
C _i		V _I = 3 V or 0					4	pF
C _o		V _O = 3 V or 0					6.5	pF

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

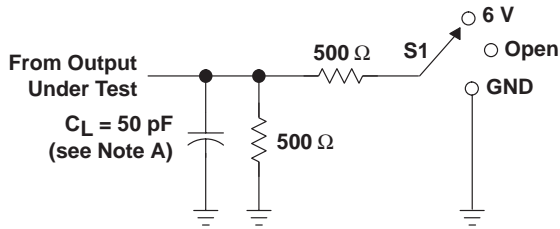
switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	TYP†	MAX	MIN	MAX	
t _{PLH}	A	Y	1	2	3.5	4.5		ns
t _{PHL}			1	2.1	3.9	4.9		
t _{PZH}	\overline{OE}	Y	1	2	4	5.5		ns
t _{PZL}			1.1	2.1	4	5.4		
t _{PHZ}	\overline{OE}	Y	1.5	2.3	4.5	5.7		ns
t _{PLZ}			1.3	2.8	4.5	4		

† All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

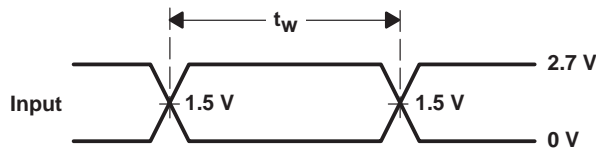


PARAMETER MEASUREMENT INFORMATION

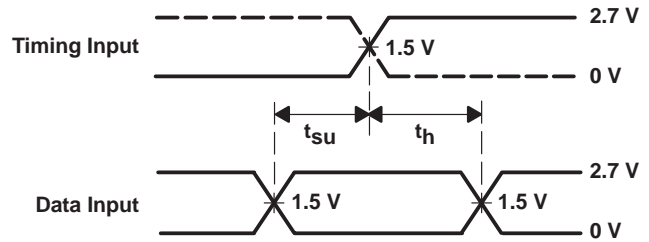


LOAD CIRCUIT

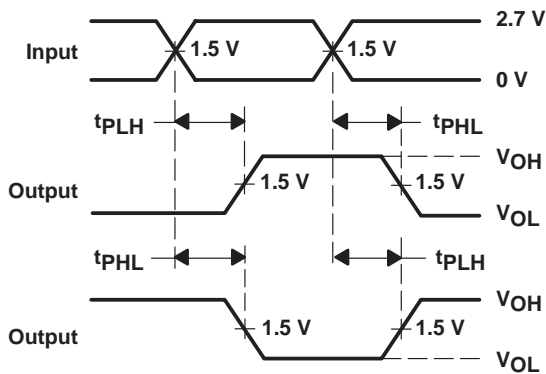
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



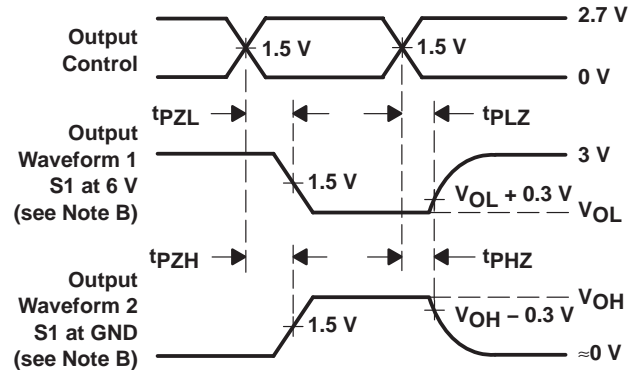
**VOLTAGE WAVEFORMS
 PULSE DURATION**



**VOLTAGE WAVEFORMS
 SETUP AND HOLD TIMES**



**VOLTAGE WAVEFORMS
 PROPAGATION DELAY TIMES
 INVERTING AND NONINVERTING OUTPUTS**



**VOLTAGE WAVEFORMS
 ENABLE AND DISABLE TIMES
 LOW- AND HIGH-LEVEL ENABLING**

- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 2.5 \text{ ns}$, $t_f \leq 2.5 \text{ ns}$.
 D. The outputs are measured one at a time with one transition per measurement.
 E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVTH125IPWREP	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH125EP	Samples
V62/04671-01XE	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LH125EP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF SN74LVTH125-EP :

- Catalog: [SN74LVTH125](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH125IPWREP	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH125IPWREP	TSSOP	PW	14	2000	356.0	356.0	35.0

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